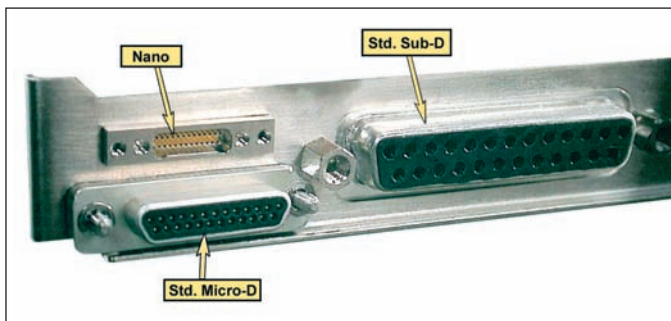
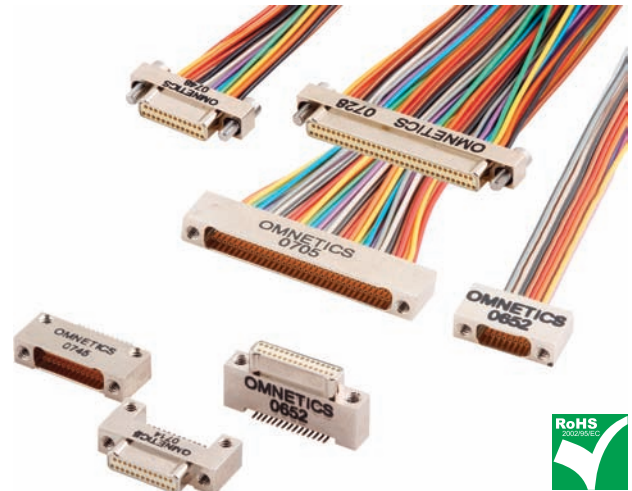


## Bi-Lobe® Connectors

### Features:

- Dual Row Metal Shell Nano Offset Connectors
- Sizes: 9-15-21-25-31-37-51-65 pins at 0,635 mm Pitch
- Mating Pin and Sockets available
- All sizes with 18 inch [45,7cm] pre-wired leads
- Colour Coded as per IAW MIL-STD-681, System 1, using ten solid repeating colours
- All sizes Horizontal Surface Mount
- All sizes Flex-Circuit Mount
- All sizes Vertical Surface Mount
- All sizes Straight Thru-Hole Mount
- All sizes Panel Mount Versions (Female Only)
- Shells are factory installed



### Nano Panel Mount Connectors

Pass tests in MIL-DTL-83513 & MIL-DTL-32139.  
 Mates with Standard MIL-32139 wired plugs.  
 Space required = 1/4 of standard Micro-D's.  
 Locks with Jackscrews to mate.  
 Military Rugged reliability while reducing size, weight and Board Space in a portable and Miniturized Circuitry.

## Tested to and Passed the Following Performance Specifications of MIL-DTL-32139

Dielectric Withstanding Voltage:	250 VAC initial, 100 VAC after Humidity
Insulation Resistance:	5000 Meg ohms min @ 100 VDC
<b>Mating/Unmating Force:</b>	<b>71 mv max @ 1 amp</b>
Temperature Cycling:	-55°C to +125°C, 5 cycles
Humidity (Mated):	Per EIA-364, producedure 31-B, except omit steps 7A & 7B
<b>Vibration:</b>	<b>20 g's - no discontinuity greater than 10 nanoseconds*</b>
<b>Mechanical Shock:</b>	<b>100 g's - no discontinuity greater than 10 nanoseconds*</b>
<b>Durability:</b>	<b>200 cycles</b>
Contact Resistance after Durability:	65 mv max @ 2.5 amps
Mating/Unmating after Durability:	Forces not exceed 7 oz/contact
Salt Spray:	Per EIA-364, procedure 26-B
Low Level Contact Resistance after Salt Spray:	Max resistance 28 milliohms
Contact Resistance after Salt Spray:	70 mv max @ 1 amps
<b>Mating/Unmating force after Salt Spray:</b>	<b>Forces not to exceed 7 oz/contact</b>
<b>Contact Retention after Salt Spray:</b>	<b>Minimum of 2 lbs contact retention</b>
Thermal Vaccum Outgassing:	NASA SP-R-0022**
Solder Heat & Contact Retention:	360°C for 10 sec. & contacts must withstand 5 lbs retention force
Solder ability:	Per EIA-364, procedure 56

\* Tested and passed while monitoring for open circuits greater than 100 nanoseconds.

\*\* NASA requirement  
 Requiements in Blue exceed the 32139 requirements